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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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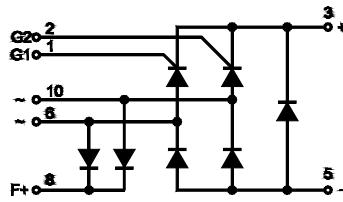
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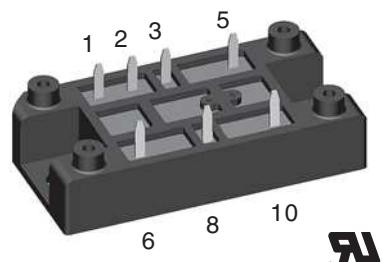
Half Controlled Single Phase Rectifier Bridge

Including Freewheeling Diode and Field Diodes

V_{RSM}	V_{RRM}	Type
V_{DSM}	V_{DRM}	
V	V	
900	800	VHFD 29-08io1
1300	1200	VHFD 29-12io1
1700	1600	VHFD 29-16io1



$V_{RRM} = 800\text{-}1600 \text{ V}$
 $I_{dAVM} = 32 \text{ A}$



Bridge and Freewheeling Diode

Symbol	Conditions	Maximum Ratings		
I_{dAV}	$T_H = 85^\circ\text{C}$, module	28	A	
$I_{dAVM} *$	module	32	A	
I_{FRMS}, I_{TRMS}	per leg	25	A	
I_{FSM}, I_{TSM}	$T_{VJ} = 45^\circ\text{C}$; $V_R = 0 \text{ V}$	300	A	
	$t = 10 \text{ ms}$ (50 Hz), sine $t = 8.3 \text{ ms}$ (60 Hz), sine	330	A	
	$T_{VJ} = T_{VJM}$ $V_R = 0 \text{ V}$	270	A	
	$t = 10 \text{ ms}$ (50 Hz), sine $t = 8.3 \text{ ms}$ (60 Hz), sine	300	A	
I^2t	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0 \text{ V}$	440	A^2s	
		455	A^2s	
	$T_{VJ} = T_{VJM}$ $V_R = 0 \text{ V}$	365	A^2s	
		370	A^2s	
$(di/dt)_{cr}$	$T_{VJ} = 125^\circ\text{C}$ $f = 50 \text{ Hz}$, $t_p = 200 \mu\text{s}$ $V_D = 2/3 V_{DRM}$ $I_G = 0.3 \text{ A}$, $di_G/dt = 0.3 \text{ A}/\mu\text{s}$	repetitive, $I_T = 50 \text{ A}$ non repetitive, $I_T = 0.5 I_{dAV}$	150	$\text{A}/\mu\text{s}$
$(dv/dt)_{cr}$	$T_{VJ} = T_{(v)im}$; $V_{DR} = 2/3 V_{DRM}$ $R_{GK} = \infty$; method 1 (linear voltage rise)	1000	$\text{V}/\mu\text{s}$	
V_{RGM}		10	V	
P_{GM}	$T_{VJ} = T_{VJM}$ $I_T = 0.5 I_{dAVM}$	$t_p = 30 \mu\text{s}$ $t_p = 500 \mu\text{s}$ $t_p = 10 \text{ ms}$	≤ 10 ≤ 5 ≤ 1	W
P_{GAVM}			0.5	W
T_{VJ}			-40...+125	$^\circ\text{C}$
T_{VJM}			125	$^\circ\text{C}$
T_{stg}			-40...+125	$^\circ\text{C}$
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	$t = 1 \text{ min}$ $t = 1 \text{ s}$	3000 3600	V_\sim
d_s	Creep distance on surface		12.7	mm
d_A	Strike distance in air		9.4	mm
a	Max. allowable acceleration		50	m/s^2
M_d	Mounting torque (M5) (10-32 UNF)		2-2.5 18-22	Nm lb.in.
Weight			35	g

Features

- Package with DCB ceramic base plate
- Isolation voltage 3600 V \sim
- Planar passivated chips
- Blocking voltage up to 1600 V
- Low forward voltage drop
- Leads suitable for PC board soldering
- UL registered E 72873

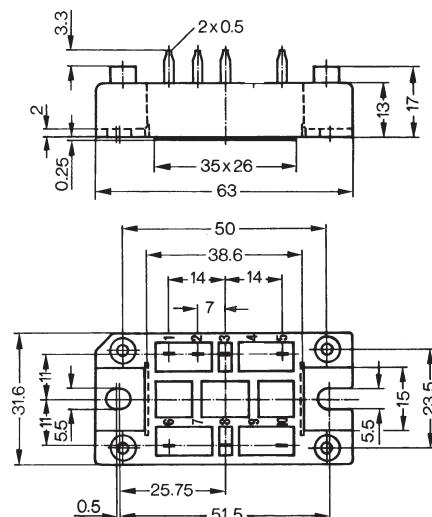
Applications

- Supply for DC power equipment
- DC motor control

Advantages

- Easy to mount with two screws
- Space and weight savings
- Improved temperature and power cycling

Dimensions in mm (1 mm = 0.0394")



Symbol	Conditions	Characteristic Values		
I_R, I_D	$V_R = V_{RRM}; V_D = V_{DRM}$ $T_{VJ} = T_{VJM}$ $T_{VJ} = 25^\circ C$	\leq	5	mA
		\leq	0.3	mA
V_T, V_F	$I_T, I_F = 45 A; T_{VJ} = 25^\circ C$	\leq	1.6	V
V_{TO}	For power-loss calculations only ($T_{VJ} = 125^\circ C$)	0.9	V	
r_T		15	mΩ	
V_{GT}	$V_D = 6 V;$ $T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$	\leq	1.0	V
	$T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$ $T_{VJ} = 125^\circ C$	\leq	1.2	V
I_{GT}	$V_D = 6 V;$ $T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$ $T_{VJ} = 125^\circ C$	\leq	65	mA
	$T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$ $T_{VJ} = 125^\circ C$	\leq	80	mA
		\leq	50	mA
V_{GD}	$T_{VJ} = T_{VJM};$ $T_{VJ} = T_{VJM};$	\leq	0.2	V
I_{GD}	$V_D = 2/3 V_{DRM}$ $V_D = 2/3 V_{DRM}$	\leq	5	mA
I_L	$I_G = 0.3 A; t_G = 30 \mu s;$ $di_G/dt = 0.3 A/\mu s;$ $T_{VJ} = 25^\circ C$ $T_{VJ} = -40^\circ C$ $T_{VJ} = 125^\circ C$	\leq	150	mA
	$T_{VJ} = -40^\circ C$ $T_{VJ} = 125^\circ C$	\leq	200	mA
		\leq	100	mA
I_H	$T_{VJ} = 25^\circ C; V_D = 6 V; R_{GK} = \infty$	\leq	100	mA
t_{gd}	$T_{VJ} = 25^\circ C; V_D = 0.5V_{DRM}$ $I_G = 0.3 A; di_G/dt = 0.3 A/\mu s$	\leq	2	μs
t_q	$T_{VJ} = 125^\circ C, I_T = 15 A, t_p = 300 \mu s, V_R = 100 V$	typ.	150	μs
Q_r	$di/dt = -10 A/\mu s, dv/dt = 20 V/\mu s, V_D = 2/3 V_{DRM}$		75	μC
R_{thJC}	per thyristor (diode); DC current		1.4	K/W
	per module		0.35	K/W
R_{thJH}	per thyristor (diode); DC current		2.0	K/W
	per module		0.5	K/W

Field Diodes

Symbol	Conditions	Maximum Ratings		
I_{FAV}	$T_H = 85^\circ C$, per Diode	4	A	
I_{FAVM}	per diode	4	A	
I_{FRMS}	per diode	6	A	
I_{FSM}	$T_{VJ} = 45^\circ C; V_R = 0 V$ $t = 10 ms (50 Hz), sine$ $t = 8.3 ms (60 Hz), sine$	100	A	
	$T_{VJ} = T_{VJM}$ $V_R = 0 V$ $t = 10 ms (50 Hz), sine$ $t = 8.3 ms (60 Hz), sine$	110	A	
I^2t	$T_{VJ} = 45^\circ C$ $V_R = 0 V$ $t = 10 ms (50 Hz), sine$ $t = 8.3 ms (60 Hz), sine$	50	A^2s	
	$T_{VJ} = T_{VJM}$ $V_R = 0 V$ $t = 10 ms (50 Hz), sine$ $t = 8.3 ms (60 Hz), sine$	50	A^2s	
		36	A^2s	
		37	A^2s	
I_R	$V_R = V_{RRM}$	$T_{VJ} = T_{VJM}$	1	mA
		$T_{VJ} = 25^\circ C$	0.15	mA
V_F	$I_F = 21 A; T_{VJ} = 25^\circ C$	1.83	V	
V_{TO}	For power-loss calculations only ($T_{VJ} = 125^\circ C$)	0.9	V	
r_T		50	mΩ	
R_{thJC}	per diode; DC current	4.4	K/W	
R_{thJH}	per diode; DC current	5.2	K/W	

Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.

* for resistive load

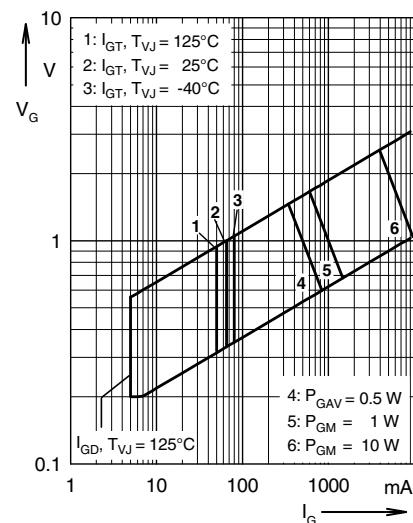


Fig. 1 Gate trigger range

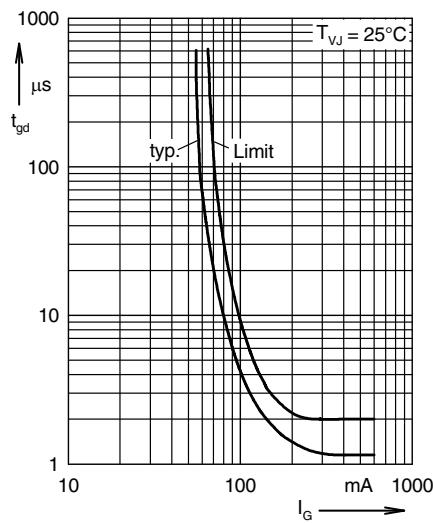


Fig. 2 Gate controlled delay time t_{gd}

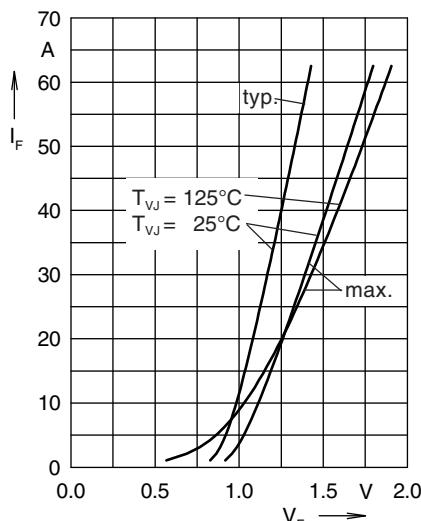


Fig. 3 Forward current vs. voltage drop per diode

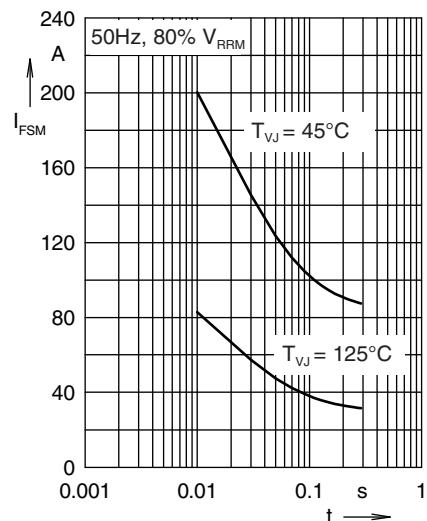


Fig. 4 Surge overload current

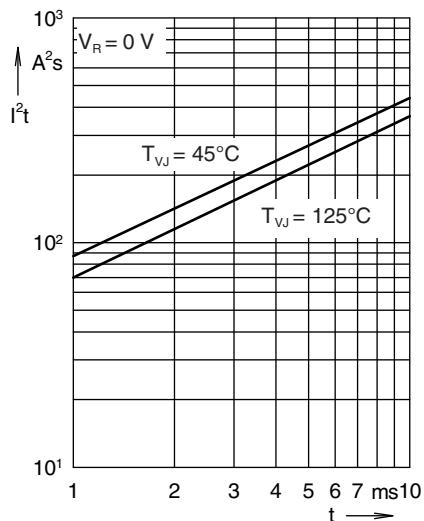


Fig. 5 I^2t versus time per diode

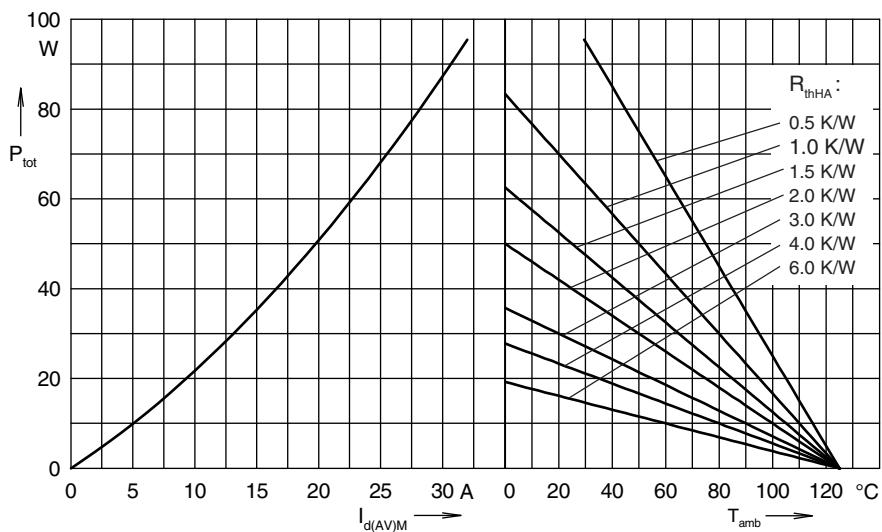


Fig. 6 Power dissipation vs. direct output current and ambient temperature

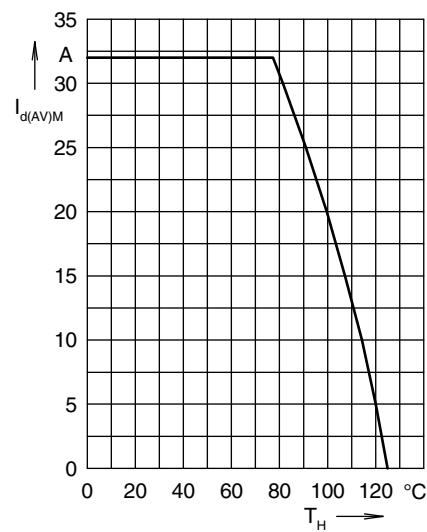


Fig. 7 Max. forward current vs. heatsink temperature

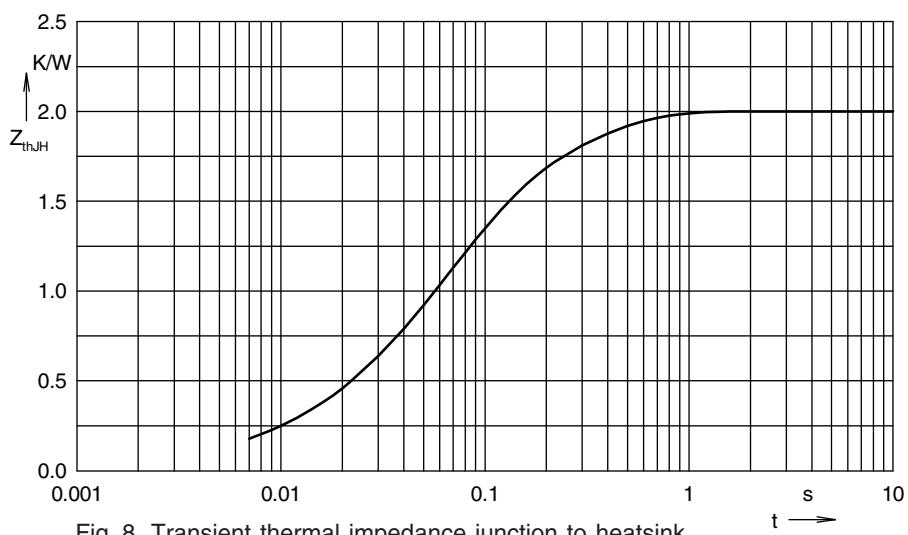


Fig. 8 Transient thermal impedance junction to heatsink

Constants for Z_{thJH} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.007	0.008
2	0.266	0.05
3	1.127	0.06
4	0.6	0.25